

**ADHESIVE COMPOSITIONS CONTAINING ORGANIC SPACERS AND METHODS  
FOR USE THEREOF**

**ABSTRACT**

In accordance with the present invention, there are provided adhesive compositions and methods for use thereof, comprising at least one maleimide-containing monomer, at least one cure initiator, and a plurality of spacer elements constructed from one or more organic polymers. Invention adhesive compositions are useful for controlling bond line thickness and planarity between a device and a substrate. Bond line thickness and planarity is largely determined by the size of the spacer elements in the adhesive composition.

2002200467800